

## **Assignment 1: Modelling of Field Effect Nano Devices (EEE 477)**

From the Nano-hub Nano TCAD ViDES Tool choose the following parameters for Symmetric Double Gated Silicon Nanowire Transistor simulations:

Channel length: 10 nm

Channel width: 4 nm

Channel height: 4 nm

Supply Voltages: 0.6 V

Source/Drain Overlap: 1 nm

Source/Drain Doping:  $1 \times 10^{18} \text{ cm}^{-3}$

Source/Drain Length: 10 nm

Keep all other device/simulation parameters at default values.

Find out the following and incorporate the figure of your simulated I-V characteristics to support your analysis

Perform a comparative transfer characteristics simulations for the below cases keeping  $V_{DS} = 0.3 \text{ V}$  and  $0.6 \text{ V}$ . In symmetric Front and Back Gates

**Effective Oxide Thickness** corresponding to 10 nm physical thickness of  $\text{HfO}_2$  ( $k=20$ )

**Effective Oxide Thickness** corresponding to 5 nm physical thickness of  $\text{HfO}_2$  ( $k=20$ )

- i) Note the  $I_{on}$  and  $I_{off}$  for  $V_{DS} = 0.6 \text{ V}$  for each of the above cases and justify your findings from a electrostatic analysis **[5M]**
- ii) Analyze the DIBL effects in each of these cases supported by simulation results **[3M]**
- iii) Suggest one device engineering technique to reduce the DIBL for the worst DIBL affected device design without changing the gate specifications and channel length **[2M]**

## **Assignment 2: Modelling of Field Effect Nano Devices (EEE 477)**

1. From the Nano-hub Nano TCAD ViDES Tool choose the following parameters for Symmetric Tri Gated Silicon Nanowire Transistor simulations:

Channel length: 10 nm

Channel width: 4 nm

Channel height: 4 nm

Gate height: 5 nm

Front Gate Effective oxide thickness: 1 nm

Back Gate Effective oxide thickness: 3 nm

Supply Voltages: 0.6 V

Source/Drain Overlap: 1 nm

Source/Drain Doping:  $1 \times 10^{18} \text{ cm}^{-3}$

Source/Drain Length: 10 nm

Keep all other device/simulation parameters at default values.

Find out the following and incorporate the figure of your simulated I-V characteristics as well as transmission spectrums to support your analysis

Perform a comparative transfer characteristics simulations for the below cases keeping  $V_{DS} = 0.6 \text{ V}$ .

Longitudinal mass = 0.1, transverse mass = 0.1

Longitudinal mass = 0.1, transverse mass = 1

Longitudinal mass = 1, transverse mass = 0.1

i) Note the  $I_{on}$  and  $I_{off}$  for each of the above cases and physically correlate your findings with effective mass [3M]

ii) Analyze the change in transmission spectrums for on-state (at  $V_{GS} = 0.5 \text{ V}$ ) condition in each of these cases [3M]

2. Based on Level-0 VSM, develop an  $I_D$ - $V_{DS}$  model for all region of applied  $V_{DS}$  of an n-channel bulk nano-MOSFET that is having 2nm thick  $\text{Si}_3\text{N}_4$  (bottom insulator) and 1 nm thick  $\text{HfO}_2$  (top insulator) stack in the gate region. [4M]